Binary to 1-8 Decoder (High)

The MC10162 is designed to convert three lines of input data to a one-of-eight output. The selected output will be high while all other outputs are low. The enable inputs, when either or both are high, force all outputs low.

The MC10162 is a true parallel decoder. No series gating is used internally, eliminating unequal delay times found in other decoders.

This device is ideally suited for demultiplexer applications. One of the two enable inputs is used as the data input, while the other is used as a data enable input.

A complete mux/demux operation on 16 bits for data distribution is illustrated in Figure 1 of the MC10161 data sheet.

- $P_D = 315 \text{ ns typ/pkg (No Load)}$
- $t_{pd} = 4.0 \text{ ns typ}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)

LOGIC DIAGRAM 4 Q2 13 Q4 11 Q6 V_{CC1} = PIN 1 V_{CC2} = PIN 16 V_{EE} = PIN 8

TRUTH TABLE

INPUTS					OUTPUTS							
Ē0	E1	С	В	Α	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7
L	L	L	L	L	Н	L	L	L	L	L	L	L
L	L	L	L	Н	L	Н	L	L	L	L	L	L
L	L	L	Н	L	L	L	Н	L	L	L	L	L
L	L	L	Н	Н	L	L	L	Н	L	L	L	L
L	L	Н	L	L	L	L	L	L	Н	L	L	L
L	L	Н	L	Н	L	L	L	L	L	Н	L	L
L	L	Н	Н	L	L	L	L	L	L	L	Н	L
L	L	Н	Н	Н	L	L	L	L	L	L	L	Н
н	Х	Х	Х	Х	L	L	L	L	L	L	L	L
X	Н	Х	Х	Х	L	L	L	L	L	L	L	L



ON Semiconductor

http://onsemi.com

MARKING DIAGRAMS



CDIP-16 **L SUFFIX CASE 620**

<u>'ŏoooooo</u> MC10162L **AWLYYWW**



PDIP-16 **P SUFFIX CASE 648** MC10162P **AWLYYWW**



PLCC-20 **FN SUFFIX CASE 775**



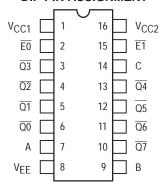
= Assembly Location

WL = Wafer Lot

= Year

WW = Work Week

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package. For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

Device	Package	Shipping
MC10162L	CDIP-16	25 Units / Rail
MC10162P	PDIP-16	25 Units / Rail
MC10162FN	PLCC-20	46 Units / Rail

MC10162

ELECTRICAL CHARACTERISTICS

						٦	Test Limits	s			
			Pin Under	-30)°C		+25°C		+8	5°C	
Characteristic		Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Current		ΙE	8		84		61	76		84	mAdc
Input Current		l _{inH}	14		350			220		220	μAdc
		l _{inL}	14	0.5		0.5			0.3		μAdc
Output Voltage	Logic 1	Voн	13	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vdc
Output Voltage	Logic 0	VOL	13 13	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdc
Threshold Voltag	ge Logic 1	Vона	13	-1.080		-0.980			-0.910		Vdc
Threshold Voltag	ge Logic 0	VOLA	13 13		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vdc
Switching Times	(50Ω Load)										ns
Propagation Del	ay	t ₁₄₊₁₃ - t ₁₄₋₁₃₊	13 13	1.5 1.5	6.2 6.2	1.5 1.5	4.0 4.0	6.0 6.0	1.5 1.5	6.4 6.4	
Rise Time	(20 to 80%)	t ₁₃₊	13	1.0	3.3	1.1	2.0	3.3	1.1	3.5	
Fall Time	(20 to 80%)	^t 13–	13	1.0	3.3	1.1	2.0	3.3	1.1	3.5	

ELECTRICAL CHARACTERISTICS (continued)

				TEST VOLTAGE VALUES (Volts)					
		@ Test Te	mperature	V _{IHmax}	V _{ILmin}	VIHAmin	V _{ILAmax}	VEE	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST V	DLTAGE API	PLIED TO PI	NS LISTED B	ELOW	
Character	istic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	VIHAmin	V _{ILAmax}	VEE	(VCC)
Power Supply Drain Current		ΙE	8					8	1,16
Input Current		linH	14	14				8	1,16
		linL	14		14			8	1,16
Output Voltage	Logic 1	Vон	13	14				8	1,16
Output Voltage	Logic 0	V _{OL}	13 13	2 15				8 8	1,16 1,16
Threshold Voltage	Logic 1	Vона	13			14		8	1,16
Threshold Voltage	Logic 0	VOLA	13 13			2 15		8 8	1,16 1,16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		^t 14+13+ ^t 14–13–	13 13			14 14	13 13	8 8	1,16 1,16
Rise Time	(20 to 80%)	t+	13			14	13	8	1,16
Fall Time	(20 to 80%)	t–	13			14	13	8	1,16

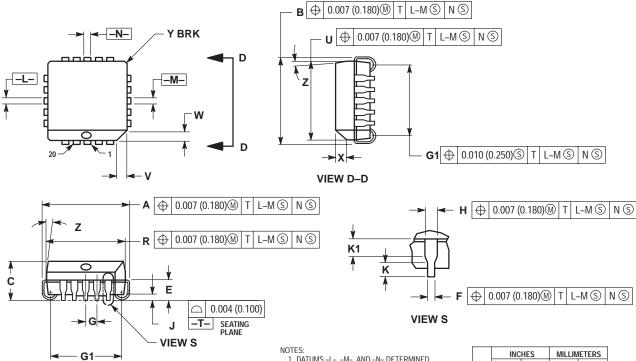
Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

MC10162

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

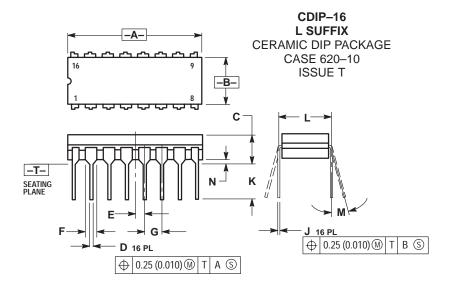
- DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTRA FRAST BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Χ	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

MC10162

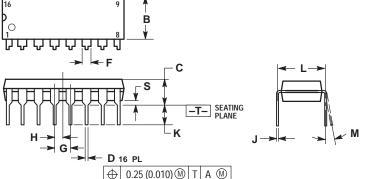


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN
- FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.750	0.785	19.05	19.93		
В	0.240	0.295	6.10	7.49		
С		0.200		5.08		
D	0.015	0.020	0.39	0.50		
Ε	0.050	BSC	1.27	BSC		
F	0.055	0.065	1.40	1.65		
G	0.100	BSC	2.54 BSC			
Н	0.008	0.015	0.21	0.38		
K	0.125	0.170	3.18	4.31		
L	0.300	BSC	7.62	BSC		
M	0°	15°	0 °	15°		
N	0.020	0.040	0.51	1.01		





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54 BSC			
Н	0.050	BSC	1.27 BSC			
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
M	0°	10°	0 °	10 °		
S	0.020	0.040	0.51	1.01		

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